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100676356

Attorney Docket Number

7426-048

TO THE HONORABLE COMMISSIONER OF PATENTS AND TRADEMARKS

Box Assignment
Washington, DC 20231

2-13-98

Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Yoshiki Sota, Koji Miyata, Toshio
Yamazaki, Fumio Inoue, Hidehiro
Nakamura, Yoshiaki Tsubomatsu,
Yasuhiko Awano, Shigeki Ichimura,
Masami Yus, and Yorio IwasakiAdditional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
- ☐ Security Agreement ☐ Change of Name
- ☐ Other _____

Execution Date: 1/9/98 and 1/12/98

2. Name and address of receiving party(ies):

Name: Hitachi Chemical Company, Ltd.
and Sharp CorporationAddress: 1-1, Nishishinjuku, 2-chome,
Shinjuku-ku, Tokyo, Japan
and
22-22, Nagaikecho, Abeno-ku,
Osaka-shi, Osaka-fu, Japan

Country (if other than USA): JAPAN

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s) 08/903,996 filed
July 31, 1997

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

PENNIE & EDMONDS LLP
1155 Avenue of the Americas
New York, NY 10036

6. Number of applications and patents involved: one

7. Total fee (37 CFR 3.41): \$ 40.00
Please charge to the deposit account listed in Section 8.8. Deposit account number:
16-1150

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Charles E. Miller 24,576
Name of Person Signing Reg. No.

Signature

Date

Total number of pages including cover sheet:

04

Mail documents to be recorded with required cover sheet information to:
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PENY4 667250.1

ASSIGNMENT

WHEREAS, WE, Yoshiki Sota, Koji Miyata, Toshio Yamazaki, Fumio Inoue, Hidehiro Nakamura, Yoshiaki Tsuboratsu, Yasuhiko Awano, Shigeki Ichimura, Masami Yusa, and Yorio Iwasaki
6-13-505, Saidaijikitachi 1-chome, Nara-shi, Nara-ken, Japan;
 ASSIGNORS, citizens of Japan, residing at 7-5-13, Higashiyanarotoshimachi, Yao-shi, Osaka-fu, Japan; A203
Hitachi-Matsushiro House, 3-4-3, Matsushiro, Tsukuba-shi, Ibaraki-ken, Japan; 301 SHK II, 2-10-1,
Hanabatake, Tsukuba-shi, Ibaraki-ken, Japan; B101 Casa, 3-7-2, Niromiya, Tsukuba-shi, Ibaraki-ken, Japan;
24-2 Migimori, Tsuchiura-shi, Ibaraki-ken, Japan; B403 Hitachi-Kasei-Shihoryo, 1-15-18, Hanabatake,
Tsukuba-shi, Ibaraki-ken, Japan; 5-19-12, Ekimuraicho, Oyara-shi, Tochigi-ken, Japan; 511-1, Ichinobe,
Shimodate-shi, Ibaraki-ken, Japan; 699-14, Ozakata, Shimodate-shi, Ibaraki-ken, Japan, respectively

are the inventors of the invention in SUBSTRATE FOR HOLDING A CHIP OF SEMI-CONDUCTOR PACKAGE, SEMI-CONDUCTOR
PACKAGE, AND FABRICATION PROCESS OF SEMI-CONDUCTOR PACKAGE
 for which we have executed an application for a Patent of the United States

☐ on even date herewith and/or which is identified by Pennie & Edmonds docket no. _____
☒ which was filed on July 31, 1997, Serial No. 08/903,996

and WHEREAS, Hitachi Chemical Company, Ltd. and Sharp Corporation
are 1-1, Nishishinjuku 2-chome, Shinjuku-ku, Tokyo, Japan and
 whose address is 22-22, Nagaikecho, Abeno-ku, Osaka-shi, Osaka-fu, Japan, respectively,

ASSIGNEE, ^{are} ~~is~~ desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND WE HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States to issue any and all patents and other evidence or forms of industrial property protection on applications as aforesaid, to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention.

IN TESTIMONY WHEREOF, We hereunto set our hands and seals the day and year set below our respective signatures.

Yoshiki Sota L.S.
 [Name]
 Yoshiki SOTA

Signed and sworn to before me
 this ____ day of _____, 199_

January 9, 1998
 [Date]

 [Notary Public or U.S. Diplomatic or Consular Official]

Koji Miyata L.S.
[Name]

Koji MIYATA

January 9, 1998
[Date]

Signed and sworn to before me
this ____ day of _____, 199_

[Notary Public or U.S. Diplomatic or Consular Official]

Toshio Yamazaki L.S.
[Name]

Toshio YAMAZAKI

January 12, 1998
[Date]

Signed and sworn to before me
this ____ day of _____, 199_

[Notary Public or U.S. Diplomatic or Consular Official]

Fumio Inoue L.S.
[Name]

Fumio INOUE

January 12, 1998
[Date]

Signed and sworn to before me
this ____ day of _____, 199_

[Notary Public or U.S. Diplomatic or Consular Official]

Hidehiro Nakamura L.S.
[Name]

Hidehiro NAKAMURA

January 12, 1998
[Date]

Signed and sworn to before me
this ____ day of _____, 199_

[Notary Public or U.S. Diplomatic or Consular Official]

Yoshiaki Tsubomatsu L.S.
[Name]

Yoshiaki TSUBOMATSU

January 12, 1998
[Date]

Signed and sworn to before me
this ____ day of _____, 199_

[Notary Public or U.S. Diplomatic or Consular Official]

Yoshihiko Awano L.S.
[Name]
Yoshihiko AWANO

Signed and sworn to before me
this ____ day of _____, 199_

January 12, 1998
[Date]

[Notary Public or U.S. Diplomatic or Consular Official]

Shigeki Ichimura L.S.
[Name]
Shigeki ICHIMURA

Signed and sworn to before me
this ____ day of _____, 199_

January 12, 1998
[Date]

[Notary Public or U.S. Diplomatic or Consular Official]

Masami Yusa L.S.
[Name]
Masami YUSA

Signed and sworn to before me
this ____ day of _____, 199_

January 12, 1998
[Date]

[Notary Public or U.S. Diplomatic or Consular Official]

Yorio Iwasaki L.S.
[Name]
Yorio IWASAKI

Signed and sworn to before me
this ____ day of _____, 199_

January 12, 1998
[Date]

[Notary Public or U.S. Diplomatic or Consular Official]

[Name] L.S.

Signed and sworn to before me
this ____ day of _____, 199_

[Date]

[Notary Public or U.S. Diplomatic or Consular Official]